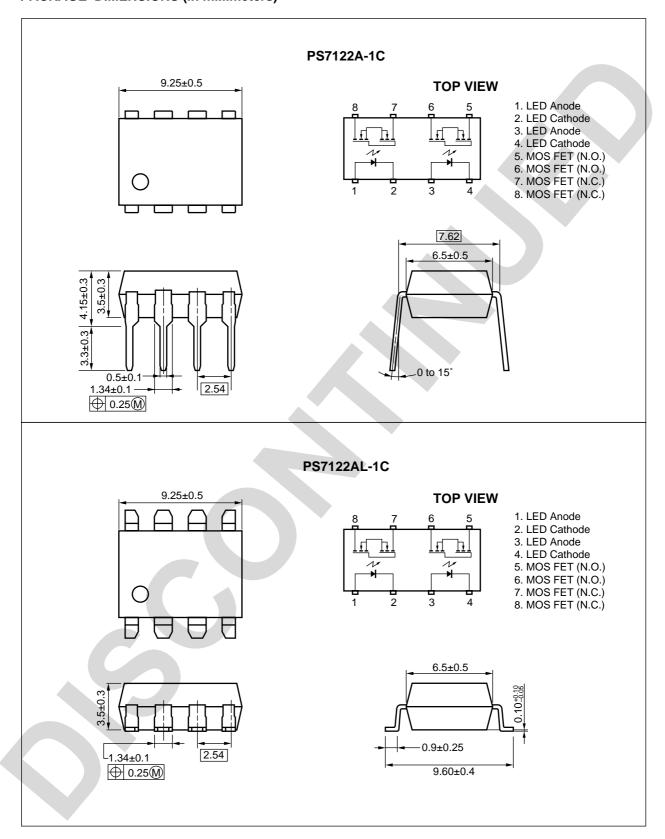
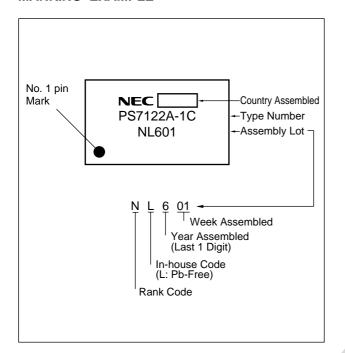
PACKAGE DIMENSIONS (in millimeters)



<R> MARKING EXAMPLE



<R> ORDERING INFORMATION

Part Number	Order Number	Solder Plating Specification	Packing Style	Safety Standard Approval	Application Part Number*1
PS7122A-1C	PS7122A-1C-A	Pb-Free	Magazine case 50 pcs	Standard products	PS7122A-1C
PS7122AL-1C	PS7122AL-1C-A			(UL, BSI, CSA	
PS7122AL-1C-E3	PS7122AL-1C-E3-A		Embossed Tape 1 000 pcs/reel	approved)	
PS7122AL-1C-E4	PS7122AL-1C-E4-A				

^{*1} For the application of the Safety Standard, following part number should be used.

ABSOLUTE MAXIMUM RATINGS (TA = 25°C, unless otherwise specified)

Parameter		Symbol	Ratings	Unit
Diode	iode Forward Current (DC)		50	mA/ch
	Reverse Voltage		5.0	V
	Power Dissipation	Po	50	mW/ch
	Peak Forward Current *1	IFP	1	A/ch
MOS FET	Break Down Voltage	VL	250	V
	Continuous Load Current	lι	200	mA/ch
	Pulse Load Current *2 (AC/DC Connection)	ILP	400	mA/ch
	Power Dissipation	Po	375	mW/ch
Isolation Voltage*3		BV	1 500	Vr.m.s.
Total Power Dissipation		Рт	850	mW
Operating Ambient Temperature		TA	-40 to +85	°C
Storage Temperature		Tstg	-40 to +100	°C

^{*1} PW = 100 μ s, Duty Cycle = 1%

RECOMMENDED OPERATING CONDITIONS (TA = 25°C)

Parameter	Symbol	MIN.	TYP.	MAX.	Unit	
LED Operating Current	lF	2	10	20	mA	
LED Off Voltage	VF	0		0.5	V	

4

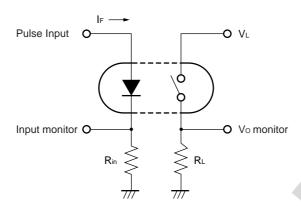
^{*2} PW = 100 ms, 1 shot

^{*3} AC voltage for 1 minute at $T_A = 25$ °C, RH = 60% between input and output Pins 1-4 shorted together, 5-8 shorted together.

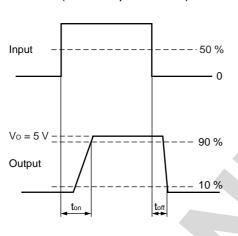
ELECTRICAL CHARACTERISTICS (TA = 25°C)

Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode Forward Voltage		VF	IF = 10 mA		1.2	1.4	V
	Reverse Current	IR	V _R = 5 V			5.0	μА
MOS FET	Off-state Leakage Current	Loff	N.O.: I _F = 0 mA, V _D = 250 V		0.03	1.0	μΑ
			N.C.: I _F = 10 mA, V _D = 250 V				
	Output Capacitance	Cout	N.O.: V _D = 0 V, f = 1 MHz		120		pF/ch
			N.C.: I _F = 10 mA, V _D = 0 V, f = 1 MHz	4	340		
Coupled	LED On-state Current	I Fon	N.O.: IL = 200 mA			2.0	mA
	LED Off-state Current	I Foff	N.C.: IL = 200 mA			2.0	mA
	On-state Resistance	R _{on1}	N.O.: IF = 10 mA, IL = 10 mA		4.5	8.0	Ω
			N.C.: IF = 0 mA, IL = 10 mA				
		Ron2	N.O.: IF = 10 mA, IL = 200 mA, $t \le 10$ ms				
			N.C.: $I_F = 0$ mA, $I_L = 200$ mA, $t \le 10$ ms				
	Turn-on Time *1, 2	ton (N.O.)	IF = 10 mA, $V_0 = 5 \text{ V}$, $R_L = 500 \Omega$,		0.5	1.5	ms
		ton (N.C.)	PW ≥ 10 ms		0.04	0.2	
	Turn-off Time *1, 2	toff (N.O.)			0.04	0.2	
		toff (N.C.)			0.5	1.5	
	Isolation Resistance	R _{I-O}	Vi-o = 1.0 kVpc	10 ⁹			Ω
	Isolation Capacitance	C _{I-O}	V = 0 V, f = 1 MHz		1.1		pF/ch

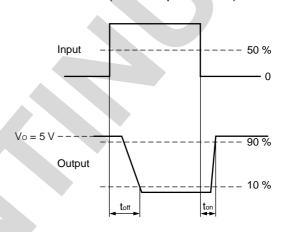
*1 Test Circuit for Switching Time



N.O. (between pin 5 and 6)



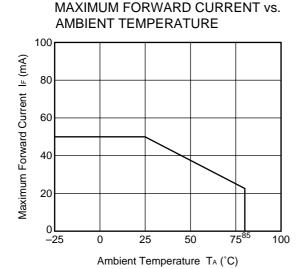
N.C. (between pin 7 and 8)

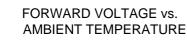


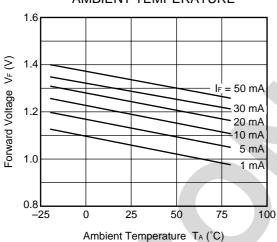
<R> *2 The turn-on time and turn-off time are specified as input-pulse width ≥ 10 ms.

Be aware that when the device operates with an input-pulse width less than 10 ms, the turn-on time and turn-off time will increase.

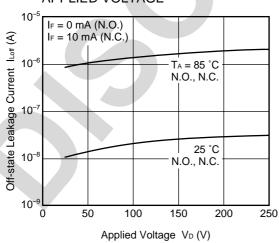
TYPICAL CHARACTERISTICS (TA = 25°C, unless otherwise specified)





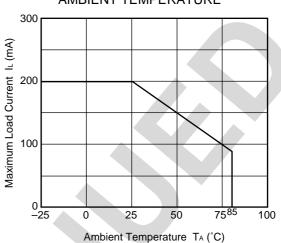


OFF-STATE LEAKAGE CURRENT vs. APPLIED VOLTAGE

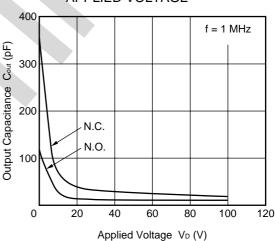


Remark The graphs indicate nominal characteristics.

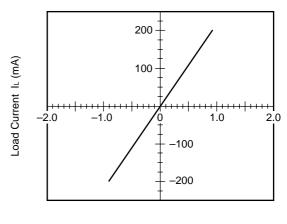




OUTPUT CAPACITANCE vs. APPLIED VOLTAGE

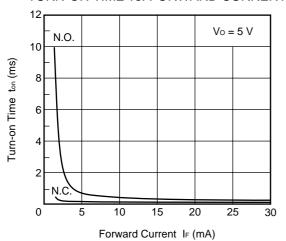


LOAD CURRENT vs. LOAD VOLTAGE

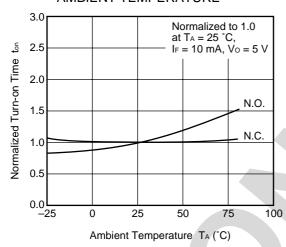


Load Voltage V_L (V)

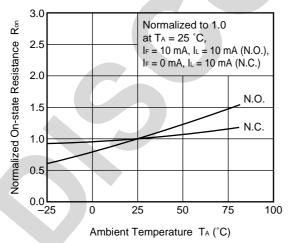
TURN-ON TIME vs. FORWARD CURRENT



NORMALIZED TURN-ON TIME vs. AMBIENT TEMPERATURE

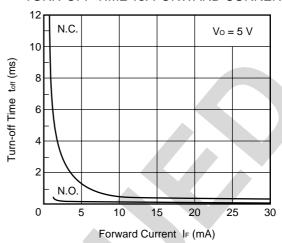


NORMALIZED ON-STATE RESISTANCE vs. AMBIENT TEMPERATURE

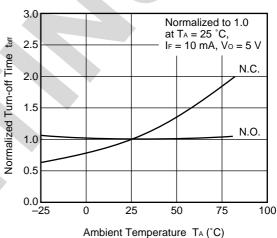


Remark The graphs indicate nominal characteristics.

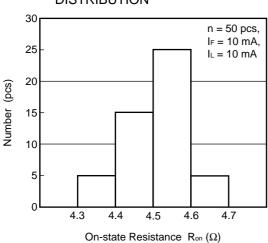
TURN-OFF TIME vs. FORWARD CURRENT



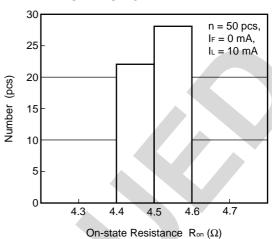
NORMALIZED TURN-OFF TIME vs. AMBIENT TEMPERATURE



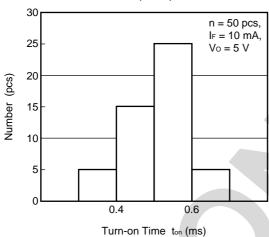
ON-STATE RESISTANCE (N.O.) DISTRIBUTION



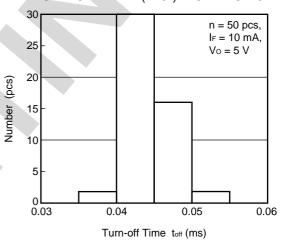
ON-STATE RESISTANCE (N.C.) DISTRIBUTION



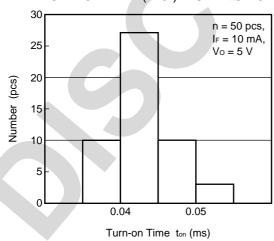
TURN-ON TIME (N.O.) DISTRIBUTION



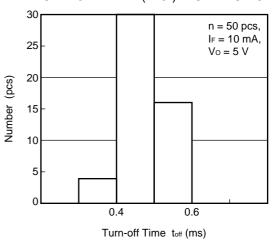
TURN-OFF TIME (N.O.) DISTRIBUTION



TURN-ON TIME (N.C.) DISTRIBUTION

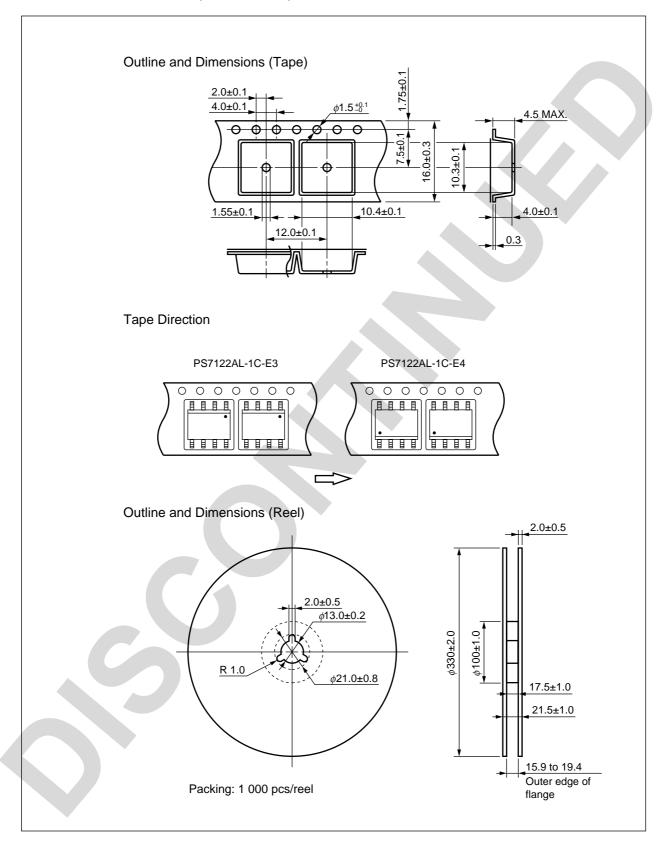


TURN-OFF TIME (N.C.) DISTRIBUTION



Remark The graphs indicate nominal characteristics.

TAPING SPECIFICATIONS (in millimeters)



RECOMMENDED SOLDERING CONDITIONS

(1) Infrared reflow soldering

Peak reflow temperature
 260°C or below (package surface temperature)

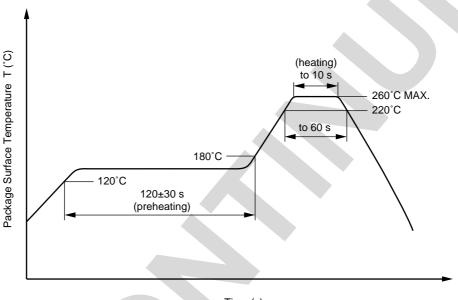
Time of peak reflow temperature
 Time of temperature higher than 220°C
 50 seconds or less
 60 seconds or less

Time to preheat temperature from 120 to 180°C 120±30 s
 Number of reflows Three

• Flux Rosin flux containing small amount of chlorine (The flux with a

maximum chlorine content of 0.2 Wt% is recommended.)

Recommended Temperature Profile of Infrared Reflow



Time (s)

(2) Wave soldering

• Temperature 260°C or below (molten solder temperature)

• Time 10 seconds or less

Preheating conditions
 120°C or below (package surface temperature)

• Number of times One

Flux
 Rosin flux containing small amount of chlorine (The flux with a maximum chlorine

content of 0.2 Wt% is recommended.)

<R> (3) Soldering by soldering iron

Peak temperature (lead part temperature)
 Time (each pins)
 350°C or below
 3 seconds or less

Rosin flux containing small amount of chlorine (The flux with a

maximum chlorine content of 0.2 Wt% is recommended.)

(a) Soldering of leads should be made at the point 1.5 to 2.0 mm from the root of the lead.

(b) Please be sure that the temperature of the package would not be heated over 100°C.

(4) Cautions

Fluxes

Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.

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<R> USAGE CAUTIONS

- 1. Protect against static electricity when handling.
- 2. Avoid storage at a high temperature and high humidity.



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M8E 02.11-1

Caution

GaAs Products

This product uses gallium arsenide (GaAs).

GaAs vapor and powder are hazardous to human health if inhaled or ingested, so please observe the following points.

- Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below.
 - Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials.
- 2. Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal.
- Do not burn, destroy, cut, crush, or chemically dissolve the product.
- Do not lick the product or in any way allow it to enter the mouth.

▶ For further information, please contact

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